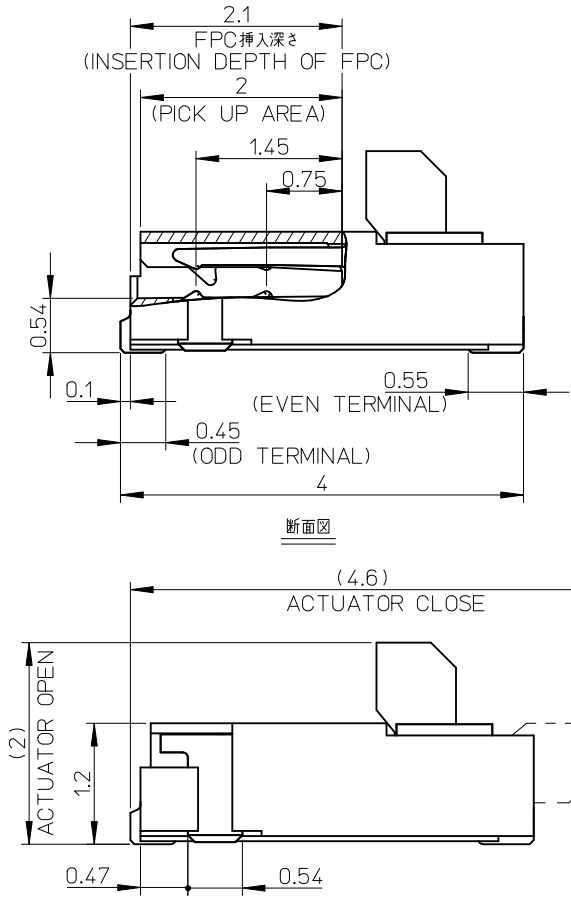
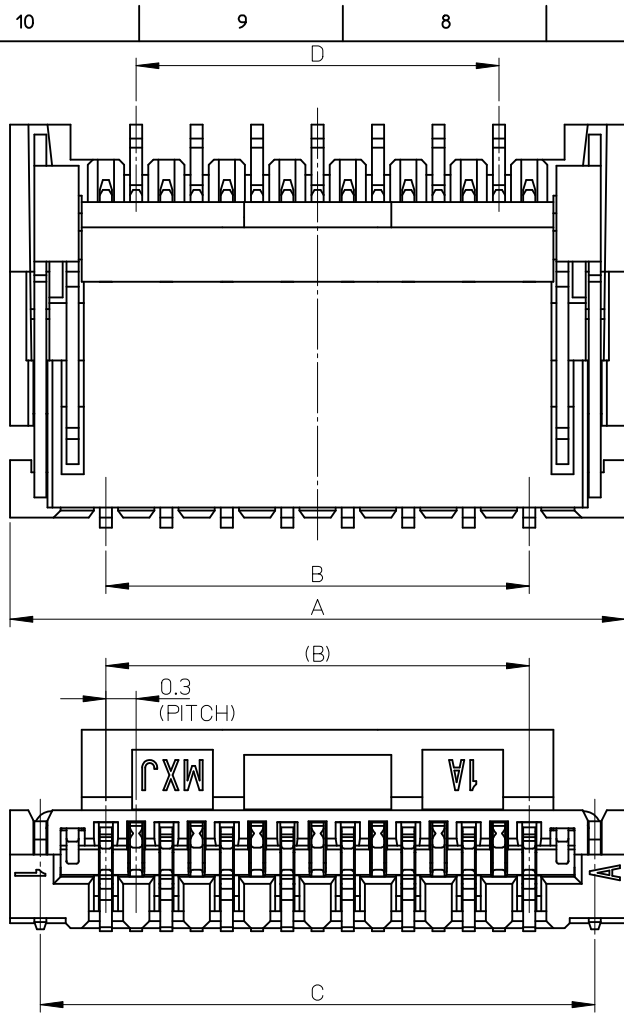




注記
NOTES:

1.材質
MATERIAL
ハウジング:液晶ポリマー(LCP)、ナチュラル(白)、ガラス充填、UL94V-0
HOUSING:LIQUID CRYSTAL POLYMER(LCP),NATURAL(WHITE)
GLASS FILLED,UL94V-0
アクチュエータ:ポリフェニレンサルファイド(PPS)、黒色、ガラス充填、UL94V-0
ACTUATOR:POLYPHENYLENE SULFIDE(PPS),BLACK
GLASS FILLED,UL94V-0
ターミナル:銅合金(t=0.12)
TERMINAL:COPPER ALLOY(t=0.12)
金具:リン青銅(t=0.12)
NAIL:PHOS-BRO(t=0.12)

2.めっき仕様
PLATING
ターミナル
TERMINAL
接点部:金めっき 0.1μm以上
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM.
半田付け部:金めっき
SOLDER TAIL AREA: GOLD
下地めっき:ニッケル 1.0μm以上
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM.
金具
NAIL
銅めっき 1.0μm以上
TIN PLATING 1.0 MICROMETER MINIMUM.
下地めっき:ニッケル 1.0μm以上
UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM.

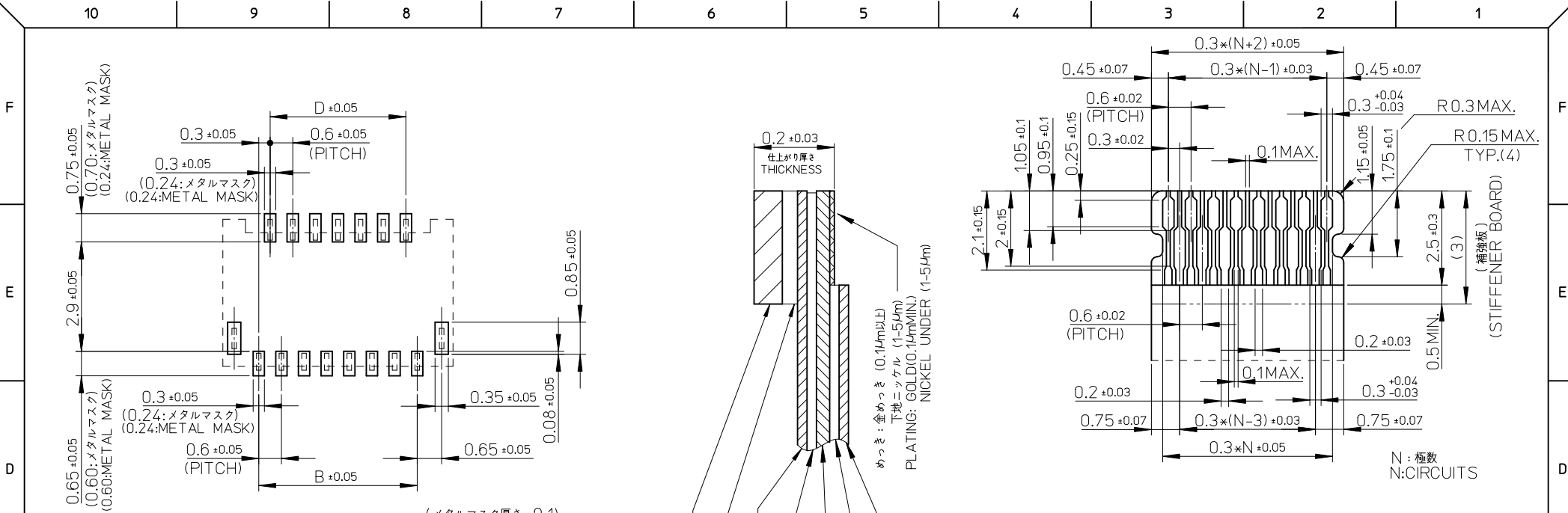
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

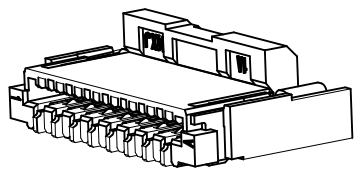
0.208	21.6	23.5	22.2	24.1	503425-7591	75
0.171	17.4	19.3	18.0	19.9	503425-6191	61
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極 数 CIRCUITS

CONNECTOR SERIES No. 503425-**11

RELEASED EC NO: J2010-2422 2009/04/28 DRWN:KUSATO 2010/05/28 CHKD:HSHIMOYAMA 2010/05/31 APPR:KMORI KAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY KUSATO	DATE 2008/11/14	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY				
		10 OVER 30 UNDER	± 0.25	CHECKED BY HSHIMOYAMA	DATE 2008/11/14					
		30 OVER	± 0.3	APPROVED BY HHIRATA	DATE 2008/11/14					
		ANGULAR ±1 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-503425-001			1 OF 2	
	REV 0	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



推奨基板寸法
RECOMMENDED P.W.B. PATTERN LAYOUT



ISO VIEW (参考)

補強板: ポリイミド
REINFORCE BOARD: POLYIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム: ポリイミド (25μm)
BASE FILM: POLYIMIDE (25μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部: 銅箔 (35μm)
COPPER FOIL (35μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ: ポリイミド (25μm)
COVER FILM: POLYIMIDE (25μm)

FPC構成推奨仕様
STRUCTURE OF FPC

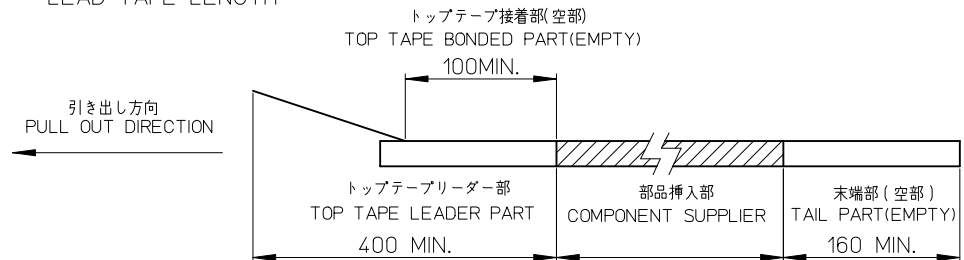
FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

SEE SHEET 1 EC NO: J2010-2422 DRAWN: KUSATO CHKD: HSHIMOYAMA APPR: KMORI KAWA O	2009/04/28 2010/05/28 2010/05/31	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	 THIRD ANGLE PROJECTION			
					MM ONLY			METRIC				
			10 UNDER	±0.2	DRAWN BY	DATE	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY					
			10 OVER 30 UNDER	±0.25	CHECKED BY	DATE						
			30 OVER	±0.3	APPROVED BY	DATE						
			ANGULAR ±1 °		MATERIAL NO.		 MOLEX INCORPORATED		DOCUMENT NO.		SHEET NO.	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE				SD-503425-001		2 OF 2	
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

注記)
NOTES

- 製品番号503425-**11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 503425-**11 DETAIL DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.
- 梱包数量:3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

5.材料

MATERIAL

キャリアテープ:ポリスチレン(PS)
CARRIER TAPE:POLYSTYRENE(PS)
トップテープ:PET, PE, PEF
TOP TAPE :PET, PE, PEF
リール:ポリスチレン
REEL:POLYSTYLENE

6.ELV及びRoHS適合品

ELV AND LoHS COMPLIANT

RELEASED EC NO: J2010-2422 DRWN:KUSATO 2008/11/19 CHKD:HSHIMOYAMA 2010/05/28 APPR:KMORIKAWA 2010/05/31	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY KUSATO	DATE 2008/11/19	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (503425-**11 SERIES) MOLEX INCORPORATED			
		10 OVER 30 UNDER	± ---	CHECKED BY HSHIMOYAMA	DATE 2008/11/19				
		30 OVER	± ---	APPROVED BY HHRATA	DATE 2008/11/19				
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1 OF 2		SD-503425-002		1 OF 2		
0	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

